

## 30V,5.2A N-Channel Power MOSFET

### GENERAL DESCRIPTION

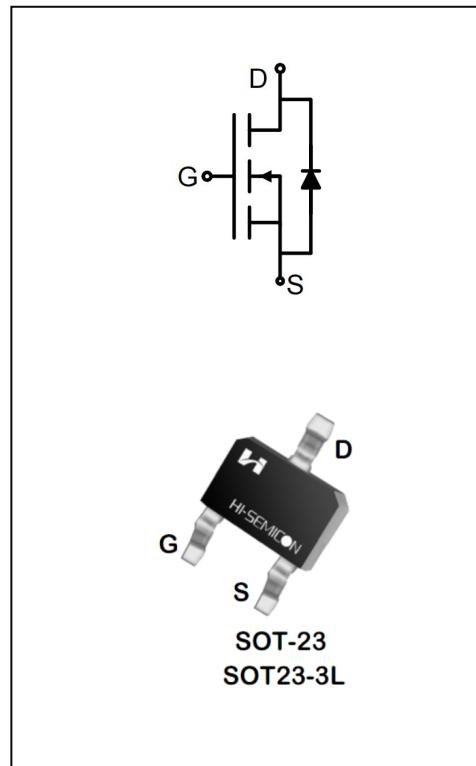
The SFS3400 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

### Features

- ◆  $V_{DS}=30V$ ,  $I_D=5.2A$
- ◆  $R_{DS(ON)}$ 
  - TYP:24.0m $\Omega$ @ $V_{GS}= 10V$ ,  $I_D= 4.0A$
  - TYP:28.0m $\Omega$ @ $V_{GS}= 4.5V$ ,  $I_D= 3.0A$
  - TYP:35.0m $\Omega$ @ $V_{GS}= 2.5V$ ,  $I_D= 3.0A$

### Applications

- ◆ Power factor correction (PFC)
- ◆ Switched mode power supplies (SMPS)
- ◆ Uninterruptible power supply (UPS)
- ◆ LED lighting power



### ORDERING INFORMATION

Part No.	Package	Marking	Material	Packing
SFS3400	SOT23-3L/SOT-23	3400	Pb Free	Reel

**ABSOLUTE MAXIMUM RATINGS (T<sub>J</sub>=25°C unless otherwise noted)**

Characteristics	Symbol	Ratings	Unit
Drain-Source Voltage	V <sub>DS</sub>	30	V
Gate-Source Voltage	V <sub>GS</sub>	±12	V
Drain Current	I <sub>D</sub>	5.2	A
T <sub>C</sub> = 75°C	I <sub>D</sub>	4.1	
Drain Current Pulsed(Note 1)	I <sub>DM</sub>	21	A
Power Dissipation(T <sub>C</sub> =25°C) -Derate above 25°C	P <sub>D</sub>	1.36	W
Operation Junction Temperature Range	T <sub>J</sub>	-55~+150	°C
Storage Temperature Range	T <sub>stg</sub>	-55~+150	°C
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T <sub>L</sub>	300	°C

**ELECTRICAL CHARACTERISTICS**

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
Drain -Source Breakdown Voltage	V <sub>BDSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	30	--	--	V
Drain-Source Leakage Current	I <sub>DS</sub>	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	--	--	1	uA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = 12V, V <sub>DS</sub> = 0V	--	--	100	nA
Gate-Source Leakage Current	I <sub>GSS</sub>	V <sub>GS</sub> = -12V, V <sub>DS</sub> = 0V	--	--	-100	
<b>On Characteristics</b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = 250μA	0.5	0.85	1.3	V
Static Drain- Source On State Resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 4.0A	--	24.0	30	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 3.0A	--	28.0	35	
		V <sub>GS</sub> = 2.5V, I <sub>D</sub> = 3.0A	--	35.0	50	
<b>Dynamic Characteristics</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 15V V <sub>GS</sub> = 0V f=1.0MHZ	--	560	--	pF
Output Capacitance	C <sub>oss</sub>		--	50	--	
Reverse Transfer Capacitance	C <sub>rss</sub>		--	45	--	
<b>Switching Characteristics</b>						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V R <sub>G</sub> = 3Ω, I <sub>D</sub> = 3.0A (Note 2.3)	--	4.7	--	nS
Turn-on Rise Time	t <sub>r</sub>		--	4.1	--	
Turn-off Delay Time	t <sub>d(off)</sub>		--	22.3	--	
Turn-off Fall Time	t <sub>f</sub>		--	3.2	--	
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> =15V, I <sub>D</sub> =4A V <sub>GS</sub> =4.5V	--	9.2	--	nC
Gate-Source Charge	Q <sub>gs</sub>		--	1.6	--	
Gate-Drain Charge	Q <sub>gd</sub>		--	3.1	--	

**SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS**

Characteristics	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Continuous Source Current	$I_S$	Integral Reverse P-N Junction Diode in the MOSFET	--	--	5.2	A
Pulsed Source Current	$I_{SM}$		--	--	21	
Diode Forward Voltage	$V_{SD}$	$I_S = 3A, V_{GS} = 0V$	--	0.8	1.2	V

NOTE:

1.Pulse width limited by maximum junction temperature

2.Pulse Test: Pulse width  $\leq 300\mu s$ , Duty cycle  $\leq 2\%$ 

3.Essentially independent of operating temperature



## Typical Performance Characteristics

Figure 1. Output Characteristics

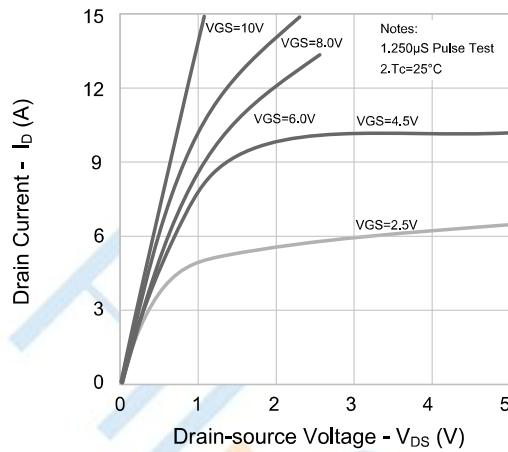


Figure 2. Transfer Characteristics

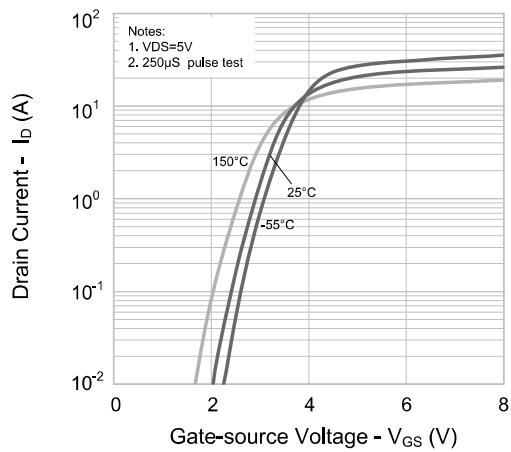


Figure 3. On-resistance vs. Drain Current

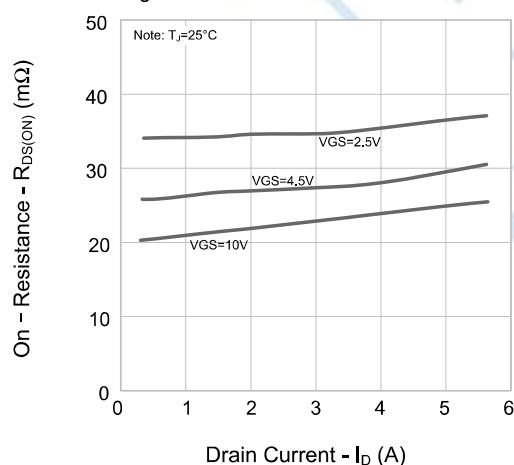


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

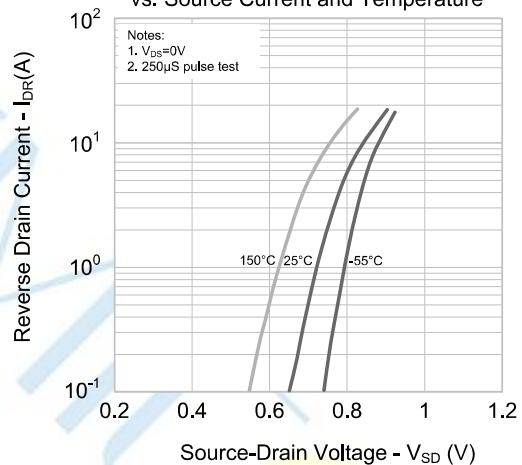


Figure 5. Capacitance Characteristics

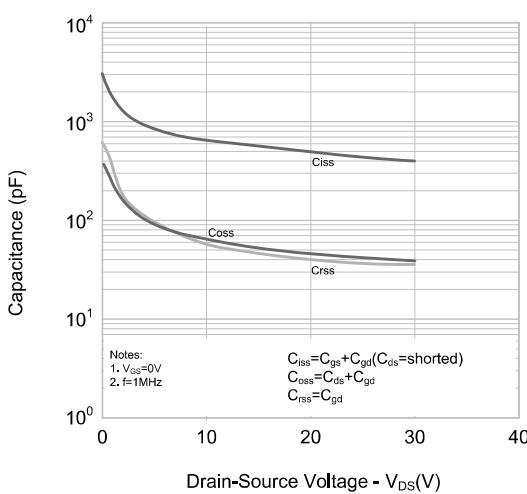
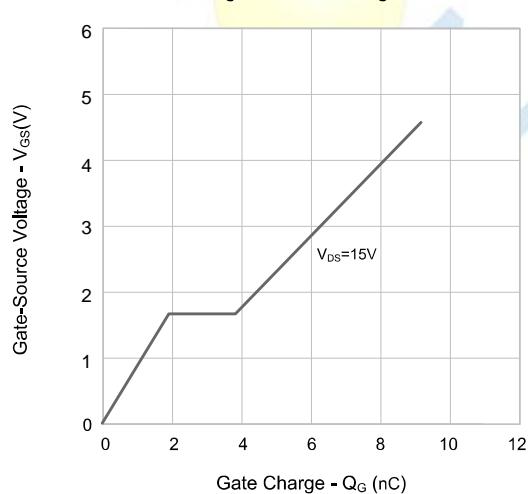
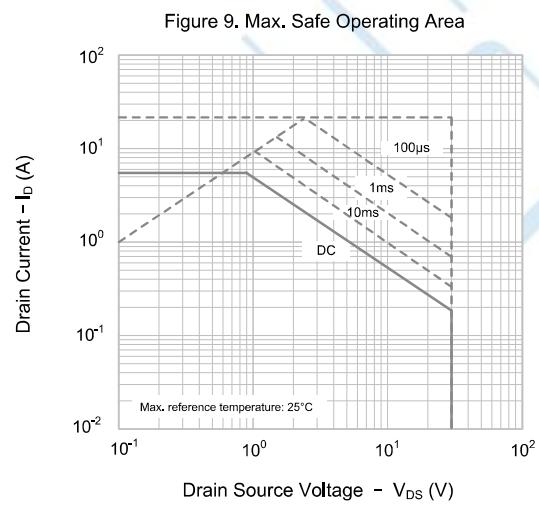
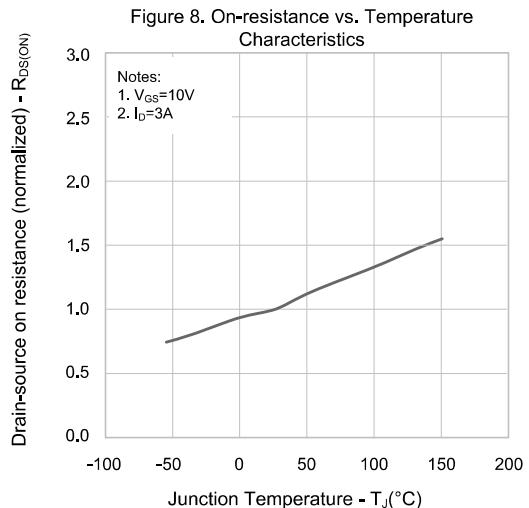
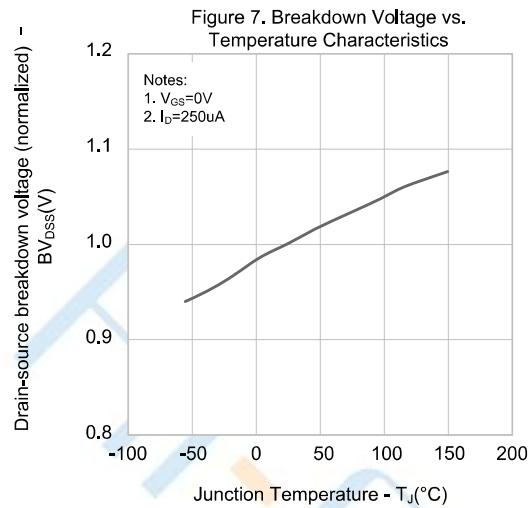


Figure 6. Gate Charge

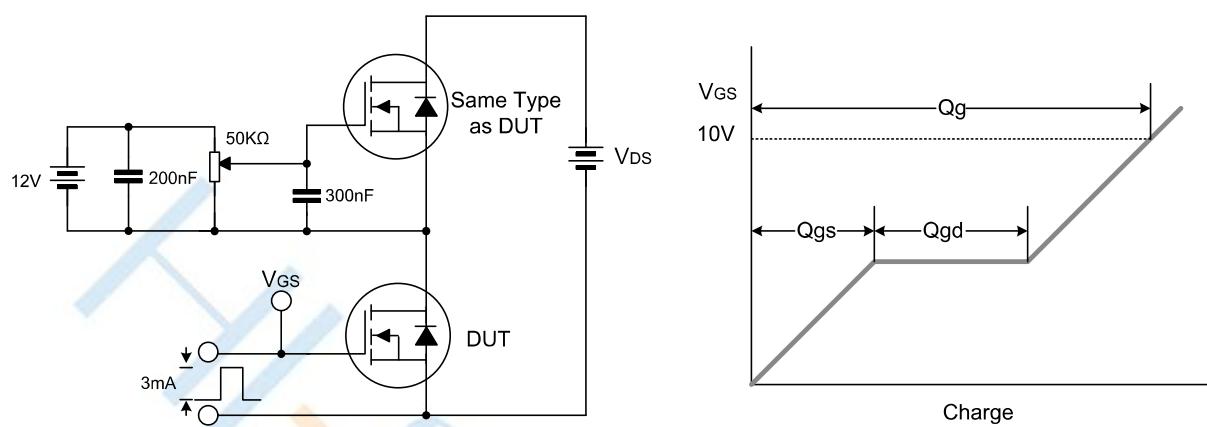


## Typical Performance Characteristics

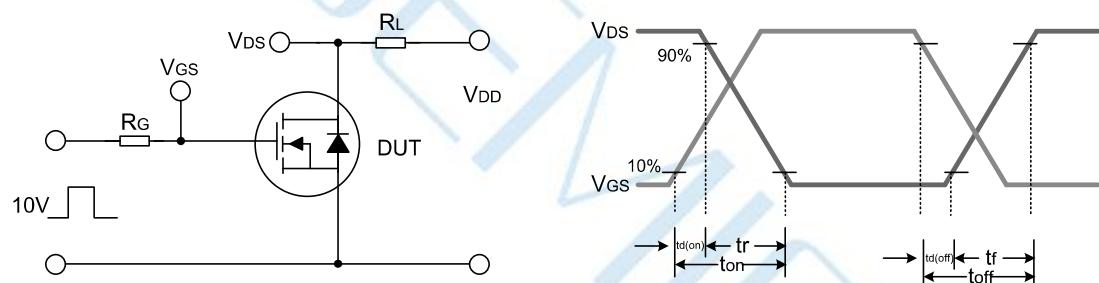


## Test Circuit

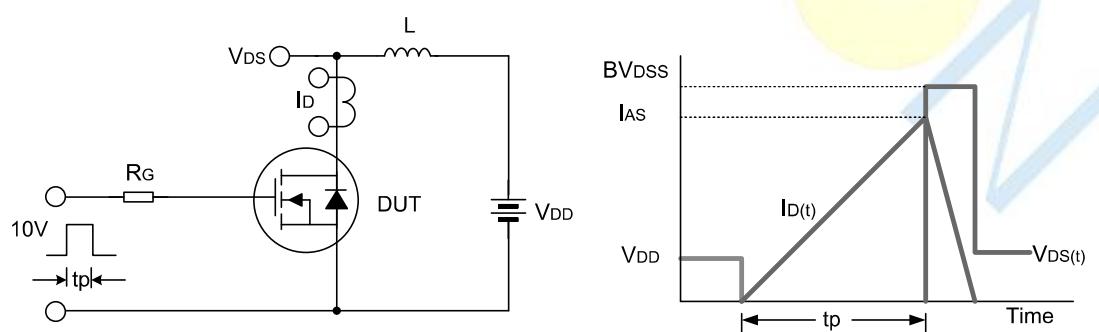
Gate Charge Test Circuit &amp; Waveform



Resistive Switching Test Circuit &amp; Waveform

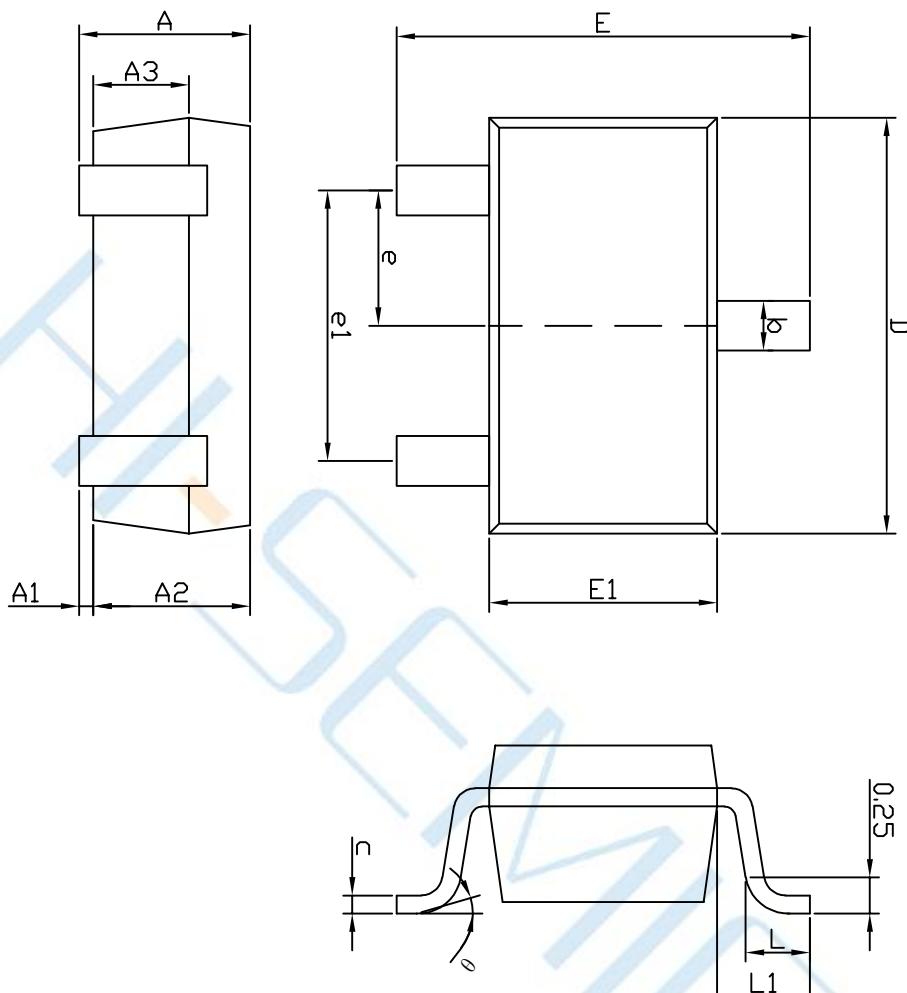


Unclamped Inductive Switching Test Circuit &amp; Waveform



## Package Dimensions of SOT23-3L

Unit:mm

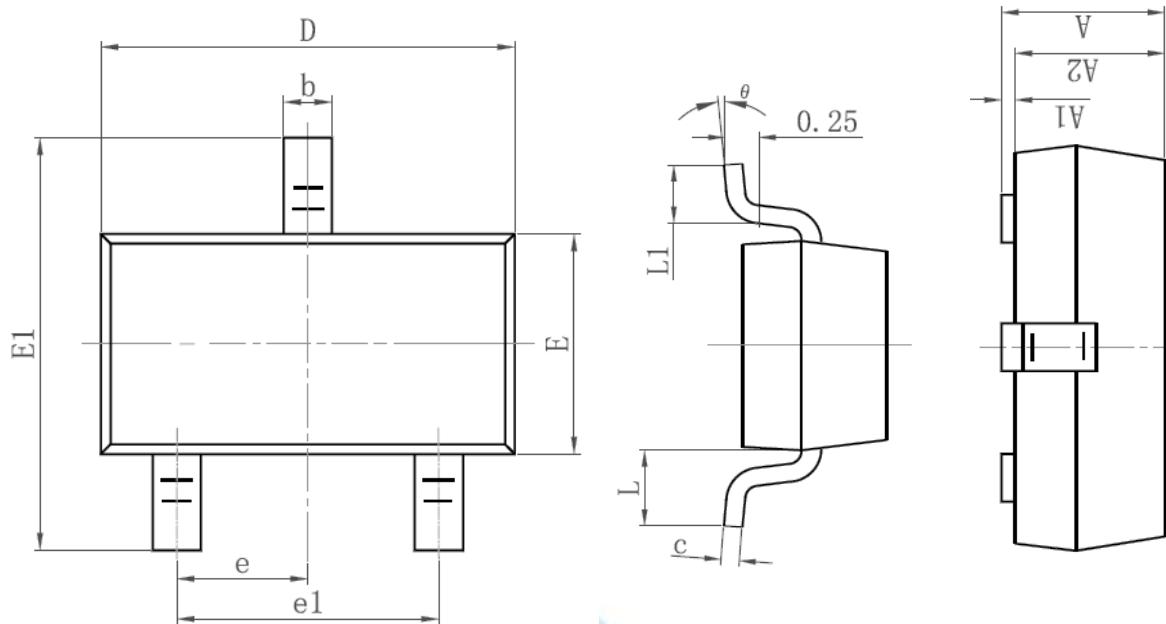


COMMON DIMENSIONS  
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	NOM	MAX
A	-	-	1.25
A1	0.04	-	0.10
A2	1.00	1.10	1.20
A3	0.60	0.65	0.70
b	0.33	-	0.41
c	0.11	-	0.20
D	2.82	2.92	3.02
E	2.60	2.80	3.00
E1	1.50	1.60	1.70
e	0.95BSC		
e1	1.90BSC		
L	0.30	-	0.60
L1	0.60REF		
θ	0°	-	8°

## Package Dimensions of SOT-23

Unit:mm



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
θ	0°	8°

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